

 Early Warning System

EIB-20250385

GLOBAL GATEWAY CHIP SUPPLY CHAIN STRENGTHENING



Quick Facts

Countries	Malaysia
Financial Institutions	European Investment Bank (EIB)
Status	Approved
Bank Risk Rating	B
Voting Date	2026-08-27
Borrower	NXP BV
Sectors	Communications, Industry and Trade
Investment Type(s)	Loan
Investment Amount (USD)	\$ 500.00 million
Loan Amount (USD)	\$ 500.00 million
Project Cost (USD)	\$ 1,103.00 million



Project Description

As stated by the EIB, the operation consists of an investment loan to support the investments of the promoter in the expansion of its chip manufacturing plant in Malaysia.

The project will reinforce the European semiconductor technology supply chain by establishing back-end operations for a key European player in the sector. This supports the EU's goal of open strategic autonomy by diversifying critical supply chains beyond geopolitical hotspots.

The operation supports a strategically important investment in the semiconductor value chain, an enabling technology essential to the EU's digital, industrial and economic resilience. Semiconductors underpin innovation and competitiveness across a wide range of sectors and are central to Europe's long-term technological leadership.

The project is aligned with the EU Chips Act, the EU's NDICI Global Gateway and the EU's objective of open strategic autonomy. While the Chips Act prioritises strengthening capacity within Europe, it also emphasises securing the full value chain through international cooperation. Supporting an EU semiconductor company's expansion in Malaysia contributes to this objective by diversifying back-end manufacturing capacity, reducing strategic dependencies and strengthening supply chain resilience.

The EIB intervenes in a context where private investment does not fully internalise the systemic risks of highly concentrated semiconductor production. Supply-chain resilience exhibits public good characteristics, as the economic costs of disruptions extend well beyond individual firms. The operation addresses this market failure by supporting diversification of critical capacity beyond geopolitical hotspots.

The EIB provides clear financial additionality through long-term financing and a flexible facility structure. Extended availability gives the borrower flexibility to manage drawdowns, strengthen its balance sheet and diversify funding beyond bond issuance, thereby supporting efficient implementation of a large-scale, policy-aligned investment.

Although located outside the EU, the investment directly supports European strategic interests. Technology ownership and core know-how remain with an EU company, strengthening Europe's semiconductor ecosystem while expanding the EU's trusted industrial footprint in Southeast Asia. At the same time, the project contributes to sustainable industrial development in the host country through skilled job creation and technology transfer, in line with the European Commission's objective to promote inclusive industrialisation and capacity building in partner countries.



Investment Description

- European Investment Bank (EIB)



Private Actors Description

As stated by Bloomberg, NXP B.V. develops and sells semiconductor devices. The Company offers amplifiers, bipolar transistors, data converters, diodes, micro controllers, power management integrated circuits, thyristors, applications processors, instrument clusters, advanced driver assistance systems, autonomous driving, and other related products. NXP serves customers worldwide.



Private Actor 1	Private Actor 1 Role	Private Actor 1 Sector	Relation	Private Actor 2	Private Actor 2 Role	Private Actor 2 Sector
-	-	-	-	NXP B.V.	Client	Industry and Trade



Contact Information

No project contacts provided at the time of disclosure.

ACCESS TO INFORMATION

You can submit an information request for project information at: <https://www.eib.org/en/infocentre/registers/request-form/request-form-default.htm>

ACCOUNTABILITY MECHANISM OF EIB

The EIB Complaints Mechanism is designed to facilitate and handle complaints against the EIB by individuals, organizations or corporations affected by EIB activities. When exercising the right to lodge a complaint against the EIB, any member of the public has access to a two-tier procedure, one internal - the Complaints Mechanism Office - and one external - the European Ombudsman. A complaint can be lodged via a written communication addressed to the Secretary General of the EIB, via email to the dedicated email address: complaints@eib.org, by completing the online complaint form available at the following address: <http://www.eib.org/complaints/form> via fax or delivered directly to the EIB Complaints Mechanism Division, any EIB local representation office or any EIB staff. For further details, check: http://www.eib.org/attachments/strategies/complaints_mechanism_policy_en.pdf

When dissatisfied with a complaint to the EIB Complaints Mechanism, citizens can then turn towards the European Ombudsman. A memorandum of Understanding has been signed between the EIB and the European Ombudsman establishes that citizens (even outside of the EU if the Ombudsman finds their complaint justified) can turn towards the Ombudsman on issues related to 'maladministration' by the EIB. Note that before going to the Ombudsman, an attempt must be made to resolve the case by contacting the EIB. In addition, the complaint must be made within two years of the date when the facts on which your complaint is based became known to you. You can write to the Ombudsman in any of the languages of the European Union. Additional details, including filing requirements and complaint forms, are available at: <http://www.ombudsman.europa.eu/atyourservice/interactiveguide.faces>



Bank Documents

- [10/09/2026 ESDS-GLOBAL GATEWAY CHIP SUPPLY CHAIN STRENGTHENING](#)



Other Related Projects

- EIB-20240024 NXP EUROPEAN SEMICONDUCTOR RDI